## PMP30331 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C2, C10	3	10uF	GRM32ER71H106KA12L	MuRata	CAP, CERM, 10 μF, 50 V,+/- 10%, X7R, 1210	1210
C3	1	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C5	1	1000uF	16SVPF1000M	Panasonic	CAP, Aluminum Polymer, 1000 µF, 16 V,+/- 20%, 0.012 ohm, F12, SMD, 2	F12, SMD, 2-Leads,
					Leads, Body 10.5x10.5mm, Height 12.7mm SMD	Body 10.5x10.5mm,
						Height 12.7mm
C7	1	22uF	GRM32ER71E226KE15L	MuRata	CAP, CERM, 22 µF, 25 V, +/- 10%, X7R, 1210	1210
C8	1	1uF	GRM188R71E105KA12D	MuRata	CAP, CERM, 1 μF, 25 V, +/- 10%, X7R, 0603	0603
C9	1	68uF	50SVPF68M	Panasonic	CAP, Aluminum Polymer, 68 µF, 50 V,+/- 20%, 0.02 ohm, F12, SMD, 2-	F12, SMD, 2-Leads,
					Leads, Body 10.5x10.5mm, Height 12.7mm SMD	Body 10.5x10.5mm,
						Height 12.7mm
C11, C19	2	0.47uF	GRM188R71E474KA12D	MuRata	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	0603
C12, C13	2	1000pF	GRM188R71H102KA01D	MuRata	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	0603
C14	1	4.7uF	GRM31CR71H475KA12L	MuRata	CAP, CERM, 4.7 µF, 50 V,+/- 10%, X7R, 1206	1206
C15	1	1uF	C1608X7R1C105K080AC	TDK	CAP, CERM, 1 µF, 16 V, +/- 10%, X7R, 0603	0603
C16	1	0.01uF	GRM188R71H103KA01D	MuRata	CAP, CERM, 0.01 μF, 50 V, +/- 10%, X7R, 0603	0603
C17	1	47pF	GRM1885C1H470JA01D	MuRata	CAP, CERM, 47 pF, 50 V,+/- 5%, C0G/NP0, 0603	0603
C18	1	0.1uF	C1608X7R1H104K080AA	TDK	CAP, CERM, 0.1 μF, 50 V, +/- 10%, X7R, 0603	0603
C20	1	10uF	GRM31CR71E106KA12L	MuRata	CAP, CERM, 10 μF, 25 V, +/- 10%, X7R, 1206	1206
C30	1	470pF	08051C471KAT2A	AVX	CAP, CERM, 470 pF, 100 V, +/- 10%, X7R, 0805	0805
C31	1	22pF	GRM1885C1H220JA01D	MuRata	CAP, CERM, 22 pF, 50 V,+/- 5%, C0G/NP0, 0603	0603
D1, D2	2	80V	MBR0580-TP	Micro Commercial Componen	Diode, Schottky, 80 V, 0.5 A, SOD-123	SOD-123
D3	1	60V	B560C-13-F		Diode, Schottky, 60 V, 5 A, SMC	SMC
D20	1	80V	DNI		Diode, Schottky, 80 V, 0.5 A, SOD-123	SOD-123
D21	1	80V	SHORT		Diode, Schottky, 80 V, 0.5 A, SOD-123	SOD-123
D100	1	30V	BAT54WS-7-F	Diodes Inc.	Diode, Schottky, 30 V, 0.2 A, SOD-323	SOD-323
J1, J2	2		1725656	Phoenix Contact	Terminal Block, 100mil, 2x1, 6A, 63V, TH	6.2x8.5x5.54 mm
J3	1		PEC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Tin, TH	Header, 3 PIN,
						100mil, Tin
L1	1	10uH	MSD1583-103MEB	Coilcraft	Coupled inductor, 10 µH, 5.2 A, 0.016 ohm, SMD	IND_14.8x8.6x14.8m
						m, SMD
Q1, Q2	2	60V	BSC094N06LS5	Infineon Technologies	MOSFET, N-CH, 60 V, 46 A, PG-TDSON-8	PG-TDSON-8
R2	1	0.01	WSLP1206R0100FEA	Vishay-Dale	RES, 0.01, 1%, 1 W, 1206	1206
R3	1	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00k ohm, 1%, 0.1W, 0603	0603
R4	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
R5, R6	2	200	CRCW0603200RFKEA	Vishay-Dale	RES, 200, 1%, 0.1 W, 0603	0603
R7	1	3.3	CRCW06033R30JNEA	Vishay-Dale	RES, 3.3 ohm, 5%, 0.1W, 0603	0603
R8, R9, R10	3	31.6k	CRCW060331K6FKEA	Vishay-Dale	RES, 31.6 k, 1%, 0.1 W, 0603	0603
R11	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
R12	1	40.2k	CRCW060340K2FKEA	Vishay-Dale	RES, 40.2 k, 1%, 0.1 W, 0603	0603
R13	1	36.5k	CRCW060336K5FKEA	Vishay-Dale	RES, 36.5 k, 1%, 0.1 W, 0603	0603
R14	1	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R15	1	10.0	CRCW060310R0FKEA	Vishay-Dale	RES, 10.0, 1%, 0.1 W, 0603	0603
R30	1	10.0	PHP01206E10R0BST5	Vishay-Dale	RES, 10.0, 0.1%, 1 W, 1206	1206
TP1, TP4	2	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature
						Testpoint
TP2, TP3, TP9	3		5002	Keystone	Test Point, Miniature, White, TH	White Miniature
						Testpoint

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
TP5, TP6, TP8	3	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature
						Testpoint
TP7	1		5003	Keystone	Test Point, Miniature, Orange, TH	Orange Miniature
						Testpoint
U1	1		LM25122QPWPTQ1	Texas Instruments	Wide Input Synchronous Boost Controller with Multiple Phase Capability,	PWP0020A
					PWP0020A (TSSOP-20)	

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